

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application.

Listing of Claims:

1. (Original) A die with text deposited upon the die using semiconductor processing techniques, the die comprising:
 - a substrate which is cut from a wafer comprising a plurality of substrates;
 - a first paragraph in contact with the substrate; and
 - a second paragraph in contact with the substrate and aligned with the first paragraph in a column.
2. (Original) The die with text deposited upon the die using semiconductor processing techniques of claim 1, wherein:
 - the substrate is a semiconductor substrate; and
 - text in the column is comprised of one or more of a metal, an oxide, a polysemiconductor and a photoresist.
3. (Original) The die with text deposited upon the die using semiconductor processing techniques of claim 1, wherein the first and second paragraphs are comprised of a plurality of characters.
4. (Original) The die with text deposited upon the die using semiconductor processing techniques of claim 3, wherein each of the plurality of characters is comprised of a plurality of primitives.

5. (Original) The die with text deposited upon the die using semiconductor processing techniques of claim 1, the die further comprising:
a first character appearing in a first color; and
a second character appearing in a second color.

6. (Original) The die with text deposited upon the die using semiconductor processing techniques of claim 1, the die further comprising an image on the substrate.

7-34. (Cancelled)

35. (New) The die with text deposited upon the die using semiconductor processing techniques of claim 1, the die further comprising a third paragraph on the substrate, wherein the second and third paragraphs are arranged in two columns on the substrate.

36. (New) The die with text deposited upon the die using semiconductor processing techniques of claim 1, wherein:
a radiation source operatively engages the substrate;
a mask is generated from an electronic file;
the mask operatively engages the radiation source and the substrate; and
the mask includes a first and second paragraphs arranged in a column.

37. (New) The die with text deposited upon the die using semiconductor processing techniques of claim 1, further comprising a silhouette image in contact with the substrate and at least partially overlapping with at least one of the first or second paragraphs.

38. (New) A die with non-functional information deposited upon the die using semiconductor processing techniques, the die comprising:
a substrate which is cut from a wafer comprising a plurality of substrates;
a first paragraph deposited upon the substrate; and
a second paragraph deposited upon the substrate and aligned with the first paragraph in one or more columns.

39. (New) The die with non-functional information deposited upon the die using semiconductor processing techniques of claim 38, wherein the first paragraph is derived from an electronic file that comprises a plurality of elements corresponding to characters for the first paragraphs.

40. (New) The die with non-functional information deposited upon the die using semiconductor processing techniques of claim 39, wherein each character of the first and second paragraphs is comprised of a plurality of rectangles wherein one side of the rectangle is equal in size to the process resolution.

41. (New) The die with non-functional information deposited upon the die using semiconductor processing techniques of claim 38, wherein the first and second paragraphs are separated by at least one of: a hard return, a tab or an enlarged character.

42. (New) The die with non-functional information deposited upon the die using semiconductor processing techniques of claim 38, the die further comprising:

- a first character visible as a first color; and
- a second character visible as a second color, which is different from the first.

43. (New) The die with non-functional information deposited upon the die using semiconductor processing techniques of claim 38, further comprising a silhouette image in contact with the substrate and at least partially overlapping with at least one of the first or second paragraphs.

44. (New) The die with non-functional information deposited upon the die using semiconductor processing techniques of claim 38, wherein:

- the first paragraph is read from an electronic source;
- the second paragraph is read from the electronic source; and
- the column is generated with an electronic file.

45. (New) The die with non-functional information deposited upon the die using semiconductor processing techniques of claim 38, wherein the first paragraph is deposited using a lithographic technique that includes a mask.

46. (New) The die with non-functional information deposited upon the die using semiconductor processing techniques of claim 38, wherein the first paragraph is produced with a method comprising steps of:

converting a first character of the first paragraph into a first pattern;
converting a second character of the first paragraph into a second pattern; and
aligning the first and second characters on a line.

47. (New) The die with non-functional information deposited upon the die using semiconductor processing techniques of claim 38, wherein the substrate is a semiconductor wafer.

48. (New) The die with non-functional information deposited upon the die using semiconductor processing techniques of claim 38, wherein the first paragraph is produced with a method comprising a step of determining an end of a first line and beginning a second line.

49. (New) The die with non-functional information deposited upon the die using semiconductor processing techniques of claim 38, wherein the column is produced with a method comprising a step of determining an end of the first paragraph and beginning the second paragraph on the next line of the column.

50. (New) The die with non-functional information deposited upon the die using semiconductor processing techniques of claim 38, wherein the column is produced with a method comprising a step of detecting an end of a first column and depositing a next line in a second column.

51. (New) The die with non-functional information deposited upon the die using semiconductor processing techniques of claim 38, wherein the first paragraph is produced with a method comprising steps of:

- determining a first color for a first character; and
- determining a second color for a second character.

52. (New) A die with non-functional information deposited upon the die using semiconductor processing techniques, the die comprising:

- a substrate which is cut from a wafer comprising a plurality of substrates arranged in a grid of the wafer;
- a paragraph photolithographically deposited upon the substrate; and
- a silhouette image in contact with the substrate and at least partially overlapping with the paragraph.

53. (New) The die with non-functional information deposited upon the die using semiconductor processing techniques of claim 52, wherein the paragraph is derived from an electronic file that comprises a plurality of elements corresponding to characters for the paragraphs.

54. (New) The die with non-functional information deposited upon the die using semiconductor processing techniques of claim 52, wherein each character of the paragraph is comprised of a plurality of rectangles wherein one side of the rectangle is equal in size to the process resolution.

55. (New) The die with non-functional information deposited upon the die using semiconductor processing techniques of claim 52, the die further comprising:

- a first character visible as a first color; and
- a second character visible as a second color, which is different from the first.

56. (New) The die with non-functional information deposited upon the die using semiconductor processing techniques of claim 52, wherein:

- the first paragraph is read from an electronic source;
- the second paragraph is read from the electronic source; and
- the column is generated with an electronic file.

57. (New) The die with non-functional information deposited upon the die using semiconductor processing techniques of claim 52, wherein the first paragraph is deposited using a lithographic technique that includes a mask.

58. (New) A die with non-functional information deposited upon the die using semiconductor processing techniques, the die comprising:

- a substrate which is cut from a wafer comprising a plurality of substrates arranged in a grid of the wafer;
- a first paragraph photolithographically deposited upon the substrate;
- a second paragraph photolithographically deposited upon the substrate; and
- a silhouette image in contact with the substrate and at least partially overlapping at least one of the first or second paragraphs.

59. (New) The die with non-functional information deposited upon the die using semiconductor processing techniques of claim 58, the die further comprising:

- a first character visible as a first color; and
- a second character visible as a second color, which is different from the first.

60. (New) The die with non-functional information deposited upon the die using semiconductor processing techniques of claim 58, wherein:

- the first paragraph is read from an electronic source;
- the second paragraph is read from the electronic source; and
- the column is generated with an electronic file.

61. (New) The die with non-functional information deposited upon the die using semiconductor processing techniques of claim 58, wherein the first paragraph is deposited using a lithographic technique that includes a mask.

62. (New) A die with non-functional information deposited upon the die using semiconductor processing techniques, the die comprising:

- a substrate which is cut from a wafer comprising a plurality of substrates arranged in a grid of the wafer;

- a first paragraph photolithographically deposited upon the substrate, wherein the first and second paragraphs are comprised of a plurality of characters;

- a second paragraph photolithographically deposited upon the substrate wherein at least one of the first or second paragraphs is generated with an electronic file; and

- a silhouette image in contact with the substrate and at least partially overlapping at least one of the first or second paragraphs.